12500 TI Boulevard, MS 8640, Dallas, Texas 75243

PCN#20180329000
Qualify TI Mexico as an additional Assembly & Test site for select PDIP devices
Change Notification / Sample Request

Date: April 16, 2018
To: Newark/Farnell PCN

This is an announcement of a change to a device that is currently offered by Texas Instruments. The details of this change are on the following pages.

We request you acknowledge receipt of this notification within **30** days of the date of this notice. Lack of acknowledgement of this notice within 30 days constitutes acceptance of the change. If you require samples or additional data to support your evaluation, please request within 30 days.

The proposed first ship date is indicated on page 3 of this notification, unless customer agreement has been reached on an earlier implementation of the change.

This notice does not change the end-of-life status of any product. Should product affected be on a previously issued product withdrawal/discontinuance notice, this notification does not extend the life of that product or change the life time buy offering/discontinuance plan.

For questions regarding this notice, contact your local Field Sales Representative or the PCN Manager (PCN_ww_admin_team@list.ti.com).

Sincerely,

PCN Team
SC Business Services

20180329000
Attachment: 1

Products Affected:

The devices listed on this page are a subset of the complete list of affected devices. According to our records, these are the devices that you have purchased within the past twenty-four (24) months. The corresponding customer part number is also listed, if available.

DEVICE	CUSTOMER PART NUMBER
INA105KP	null
INA121P	null
INA125P	null
INA125PA	null
MPC508AP	null
OPA340PA	null
PGA202KP	null
PGA2311PA	null
UAF42AP	null
UC2524AN	null
UC2845AN	null
UC2845NG4	null
UC2901N	null
UC2906NG4	null
UC3524AN	null
UC3708N	null
UC3843AN	null
UC3854AN	null
UC3856N	null
UC3856NG4	null
XTR105P	null
DAC714P	null
DAC716P	null
INA101HP	null
INA121PA	null
INA2134PA	null
INA2137PA	null
MPC509AP	null
MPY634KP	null
OPA2137PA	null
OPA2244PA	null
OPA2337PA	null
OPA344PA	null
PGA203KP	null
PGA2310PA	null
PGA2311P	null
UC2525AN	null
UC28025N	null
UC2825AN	null
UC2842AN	null
UC2843AN	null
UC2843N	null
UC2844AN	null
UC2844N	null
UC2845N	null
UC2846N	null
UC2854N	null
UC2906N	null
UC3610N	null
UC3611N	null
UC3705N	null
UC3706N	null
UC3710N	null
UC3717AN	null
UC3823AN	null
UC3823N	null
UC3825AN	null

UC3825BN	null
UC3825N	null
UC3842AN	null
UC3842N	null
UC3843N	null
UC3844AN	null
UC3844N	null
UC3845AN	null
UC3845N	null
UC3852N	null
UC3853N	null
UC3854BN	null
UC3854N	null
UC3867N	null
UC3901N	null
UC3906N	null
UC3907N	null
UCC25701N	null
UCC35701N	null
UCC3806N	null
VFC320BP	null
VFC32KP	null
XTR101AP	null
XTR105PA	null
XTR110KP	null
OPA347PA	null
UC2842N	null
UC3525AN	null
UC3707N	null
UC3709N	null
UC3770BN	null
UCC35702N	null
UCC3818N	null
XTR110KPG4	null
UC2825N	null

Technical details of this Product Change follow on the next page(s).

PCN Number:	20180329000	**PCN Date:**	April 16, 2018
Title:	Qualify TI Mexico as an additional Assembly & Test site for select PDIP devices		
Customer Contact:	PCN Manager	**Dept:**	Quality Services
Proposed 1st Ship Date:	July 16, 2018	**Estimated Sample Availability:**	Provided upon Request

Change Type:

☒	Assembly Site	☐	Design	☐	Wafer Bump Site
☐	Assembly Process	☐	Data Sheet	☐	Wafer Bump Material
☐	Assembly Materials	☐	Part number change	☐	Wafer Bump Process
☐	Mechanical Specification	☒	Test Site	☐	Wafer Fab Site
☒	Packing/Shipping/Labeling	☐	Test Process	☐	Wafer Fab Materials
				☐	Wafer Fab Process

PCN Details

Description of Change:

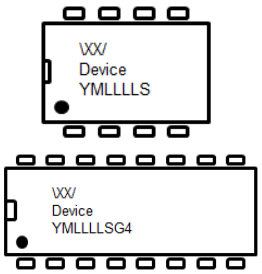
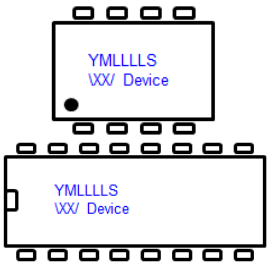
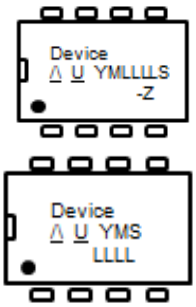
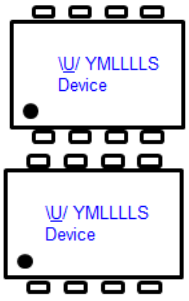
Texas Instruments is pleased to announce the qualification of TI Mexico as an additional Assembly & Test site for the list of devices shown below. Material differences between sites are as follows.

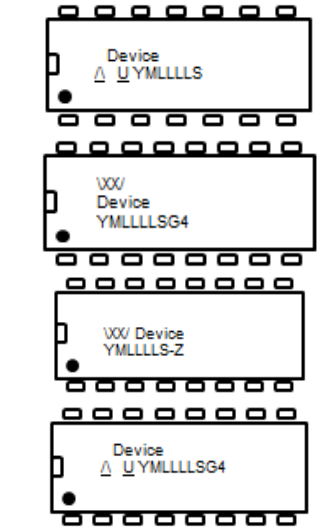
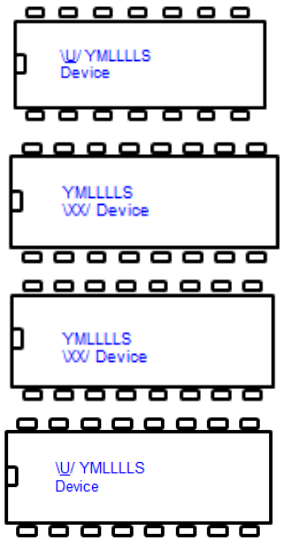
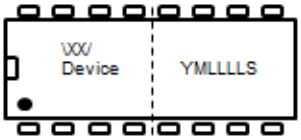
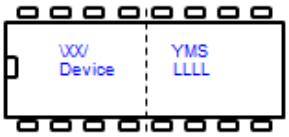
Assembly Site	Assembly Site Origin	Assembly Country Code	Assembly City
Carsem	CRS	MYS	Jelapang
TI Mexico	MEX	MEX	Aguascalientes

Material Differences:

	Carsem	TI Mexico
Mount compound	434165	4147858
Mold compound	435006	4211880
Lead finish	NiPdAu	NiPdAu

Marking Differences:

	Carsem	TI Mexico
Group 1 Device		
Group 2 Device		

			
	Group 3 Device		

Test coverage, insertions, conditions will remain consistent with current testing and verified with test MQ.

Reason for Change:

Continuity of Supply. Carsem will shut down PDIP packages by Dec2018.

Anticipated impact on Fit, Form, Function, Quality or Reliability (positive / negative):

None

Anticipated impact on Material Declaration

☐	No Impact to the Material Declaration	☒	Material Declarations or Product Content reports are driven from production data and will be available following the production release. Upon production release the revised reports can be obtained from the TI Eco-Info website. There is no impact to the material meeting current regulatory compliance requirements with this PCN change.

Changes to product identification resulting from this PCN:

Assembly Site		
Carsem	Assembly Site Origin (22L)	ASO: CRS
TI Mexico	Assembly Site Origin (22L)	ASO: MEX

Sample product shipping label (not actual product label)

Product Affected : Group 1

BQ2004EPNG4	UC2825NG4	UC3770ANG4	UC2525ANG4
BQ2004PNG4	UC2527ANG4	UC3770BNG4	UC3823ANG4
DAC714P	UC2610NG4	UC2842ANG4	UC3823NG4
DAC714PG4	UC2705NG4	UC2842NG4	UC3824NG4
DAC716PG4	UC2707NG4	UC2843ANG4	UC3825ANG4
DAC716PK	UC3843ANG4	UC2843NG4	UC3825NG4
DAC7800KPG4	UC3843NG4	UC2844ANG4	UC3854NG4
DAC7800LPG4	UC3844ANG4	UC3842ANG4	UC3856NG4
INA101HP	UC3844NG4	OPA2244PA	UC3861NG4
INA101HPG4	UC3845ANG4	OPA2244PAG4	UC3867NG4
INA105KP	UC3845NG4	OPA2337PA	UC3901NG4
INA105KPG4	UC3852NG4	OPA2337PAG4	UC3902NG4
INA121P	UC3853NG4	OPA2705PA	UC3906NG4
INA121PA	UC3854ANG4	OPA2705PAG4	UC3907NG4
INA121PAG4	UC3854BNG4	OPA340PA	UC39432NG4
INA121PG4	UC2844NG4	OPA340PAG4	UCC25701NG4
INA125P	UC2845ANG4	OPA344PA	UCC25702NG4
INA125PA	UC2845NG4	OPA344PAG4	UCC2806NG4
INA125PAG4	UC2846NG4	OPA347PA	UCC2810NG4
INA125PG4	UC2853NG4	OPA347PAG4	UCC2817ANG4
INA2134PA	UC2854ANG4	OPA4137P	UCC2818ANG4
INA2134PAG4	UC2854BNG4	OPA4137PA	UCC2818NG4
INA2137PA	UC2854NG4	OPA4137PAG4	UCC35701NG4
INA2137PAG4	UC2856NG4	OPA703PA	UCC3806NG4
MPC508AP	UC2901NG4	OPA703PAG4	UCC3817ANG4
MPC508APG4	UC2906NG4	OPA705PA	UCC3817NG4
MPC509AP	UC2907NG4	PGA202KP	UCC3818ANG4
MPC509APG4	UC29432NG4	PGA202KPG4	UCC3818NG4
MPY634KP	UC3524ANG4	PGA203KP	VFC320BPG4
MPY634KPG4	UC3525ANG4	PGA203KPG4	VFC320CPG4
OPA2137P	UC3525BNG4	PGA2310PA	VFC32KP
OPA2137PA	UC3527ANG4	PGA2310PAG4	VFC32KPG4
OPA2137PAG4	UC3610NG4	PGA2311P	XTR101AP
OPA2137PG4	UC3705NG4	PGA2311PA	XTR101APG4
UC2708NG4	UC3706NG4	PGA2311PAG4	XTR105P
UC2709NG4	UC3707NG4	PGA2311PG4	XTR105PA
UC2710NG4	UC3708NG4	SN0708100P	XTR105PAG4
UC28025NG4	UC3709NG4	UAF42AP	XTR105PG4
UC2825ANG4	UC3710NG4	UAF42APG4	XTR110KP
UC2825BNG4	UC3717ANG4	UC2524ANG4	XTR110KPG4

Product Affected : Group 2

BQ2004EPN	UC2844N	UC3717AN	UC3907N
BQ2004HPN	UC2845AN	UC3770AN	UC39432N
BQ2004PN	UC2845N	UC3770BN	UC80851N
DAC716P	UC2846N	UC3823AN	UC81185N
DAC716PB	UC2852N	UC3823N	UC81186N
UC2524AN	UC2853N	UC3824N	UC81500AN
UC2525AN	UC2854AN	UC3825AN	UC81501AN
UC2525BN	UC2854BN	UC3825BN	UC81502AN
UC2527AN	UC2854N	UC3825N	UC81521P
UC2610N	UC2856N	UC3842AN	UC81522P
UC2705N	UC2901N	UC3842N	UCC25701N
UC2706N	UC2902N	UC3843AN	UCC25702N
UC2707N	UC2906N	UC3843N	UCC2806N
UC2708N	UC2907N	UC3844AN	UCC2810N
UC2709N	UC29432N	UC3844N	UCC2817AN
UC2710N	UC3524AN	UC3845AN	UCC2817N
UC28025N	UC3525AN	UC3845N	UCC2818AN
UC2823AN	UC3525BN	UC3852N	UCC2818N
UC2823N	UC3527AN	UC3853N	UCC35701N
UC2824N	UC3610N	UC3854AN	UCC35702N
UC2825AN	UC3611N	UC3854BN	UCC3806N
UC2825BN	UC3705N	UC3854N	UCC3810N
UC2825N	UC3706N	UC3856N	UCC3817AN
UC2842AN	UC3707N	UC3861N	UCC3817N
UC2842N	UC3708N	UC3867N	UCC3818AN
UC2843AN	UC3708NE	UC3901N	UCC3818N
UC2843N	UC3709N	UC3902N	
UC2844AN	UC3710N	UC3906N	

Product Affected : Group 3

DAC7800KP	DAC7800LP	VFC320BP	VFC320CP

Qualification Report

PDIP 8/14/16 PIN OFFLOAD TO FMX Devices without Die Overcoat Polyimide

Approve Date 20-Mar-2018

Product Attributes

Attributes	Qual Device: PGA2310PA	QBS Package Reference: L293DNE	QBS Package Reference: LT1013CP	QBS Package Reference: MSP430F2013IN	QBS Package Reference: NE5532P	QBS Package Reference: SN74HC595N	QBS Package Reference: SN74HCT540N
Assembly Site	FMX	FMX	FMX	MLA	FMX	MLA	MLA
Package Family	PDIP	PDIP	PDIP	PDIP	PDIP	PDIP	PDIP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	SFAB	SFAB	SFAB	TSMC-10	SFAB	SFAB	SFAB
Wafer Fab Process	BCMOS	JI1	JI1	TSMC EMB FLASH	JI1	74HC	74HC-NONEPI

Attributes	QBS Package Reference: SN74LS03N	QBS Package Reference: TLC339IN	QBS Package Reference: TPA3122D2N	QBS Package Reference: TPS2041P	QBS Package Reference: TS12A4514P	QBS Package Reference: UCC37322P
Assembly Site	MLA	FMX	MLA	FMX	FMX	FMX
Package Family	PDIP	PDIP	PDIP	PDIP	PDIP	PDIP
Flammability Rating	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0	UL 94 V-0
Wafer Fab Supplier	SFAB	DFAB	UMC FAB8AB	DFAB	DFAB	DFAB
Wafer Fab Process	JI1	LINCMOS_5/5	LBC5X	LBC3S	LBC3S	LBC3S

- QBS: Qual By Similarity
- Qual Device PGA2310PA is qualified at Not Classified

Qualification Results

Data Displayed as: Number of lots / Total sample size / Total failed

Type	Test Name / Condition	Duration	Qual Device: PGA2310PA	QBS Package Reference: L293DNE	QBS Package Reference: LT1013CP	QBS Package Reference: MSP430F2013IN	QBS Package Reference: NE5532P	QBS Package Reference: SN74HC595N	QBS Package Reference: SN74HCT540N
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	-	3/231/0	-	3/225/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	Pass	-
FLAM	Flammability (UL 94V-0)	-	-	-	-	-	-	-	3/15/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	3/231/0	-	-
HTOL	Life Test, 150C	300 Hours	-	-	-	-	3/231/0	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0	3/231/0	-	3/231/0	-	3/231/0	3/231/0

LI	Lead Fatigue	Leads	-	3/66/0	-	3/45/0	3/66/0	3/45/0	3/45/0
LI	Lead Pull to Destruction	Leads	-	3/144/0	-	3/126/0	3/72/0	3/144/0	3/180/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass	Pass	Pass	Pass
PKG	Lead Finish Adhesion	Leads	-	3/45/0	-	3/45/0	3/45/0	3/45/0	2/30/0
SD	Solderability	8 Hours Steam Age	-	3/66/0	-	3/66/0	3/66/0	3/66/0	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/225/0	3/231/0	3/231/0	-	3/231/0	3/231/0

Type	Test Name / Condition	Duration	QBS Package Reference: SN74LS03N	QBS Package Reference: TLC339IN	QBS Package Reference: TPA3122D2N	QBS Package Reference: TPS2041P	QBS Package Reference: TS12A4514P	QBS Package Reference: UCC37322P
AC	Autoclave 121C	96 Hours	3/231/0	3/231/0	3/231/0	-	1/77/0	3/231/0
ED	Electrical Characterization	Per Datasheet Parameters	-	-	-	-	-	-
FLAM	Flammability (UL 94V-0)	-	-	-	-	-	-	3/15/0
HAST	Biased HAST, 130C/85%RH	96 Hours	-	-	-	-	-	-
HTOL	Life Test, 150C	300 Hours	-	-	-	-	-	-
HTSL	High Temp. Storage Bake, 170C	420 Hours	3/231/0	3/231/0	3/231/0	-	1/77/0	3/231/0
LI	Lead Fatigue	Leads	3/45/0	3/45/0	3/45/0	-	-	3/45/0
LI	Lead Pull to Destruction	Leads	3/126/0	3/126/0	3/180/0	-	-	3/70/0
MQ	Manufacturability (Assembly)	(per mfg. Site specification)	Pass	Pass	Pass	Pass	Pass	Pass
PKG	Lead Finish Adhesion	Leads	3/45/0	3/45/0	3/45/0	-	-	3/45/0
SD	Solderability	8 Hours Steam Age	3/66/0	3/66/0	3/66/0	-	-	3/66/0
TC	Temperature Cycle, -65/150C	500 Cycles	3/231/0	3/231/0	3/231/0	3/231/0	1/77/0	3/231/0

- Preconditioning was performed for Autoclave, Unbiased HAST, THB/Biased HAST, Temperature Cycle, Thermal Shock, and HTSL, as applicable
- The following are equivalent HTOL options based on an activation energy of 0.7eV : 125C/1k Hours, 140C/480 Hours, 150C/300 Hours, and 155C/240 Hours
- The following are equivalent HTSL options based on an activation energy of 0.7eV : 150C/1k Hours, and 170C/420 Hours
- The following are equivalent Temp Cycle options per JESD47 : -55C/125C/700 Cycles and -65C/150C/500 Cycles

Quality and Environmental data is available at TI's external Web site: http://www.ti.com/

Green/Pb-free Status:

Qualified Pb-Free(SMT) and Green

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com